

East of USPB, USPT, WPI, JPO

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|---------|--|-----------------|------------------|---------|------------------|
| L1 | 107735 | (resist or photoresist or mask or photomask).clm. | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:05 |
| L2 | 683307 | (etch\$ or patern\$ or remov\$).clm. | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:06 |
| L3 | 267478 | (bond\$ or laminat\$).clm. | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:06 |
| L4 | 502591 | (wafer or semiconduct\$ or chip or substrate).clm. | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:08 |
| L5 | 12538 | 1 with 2 with 4 | US-PGPUB; USPAT | OR | ON | 2005/10/24 18:53 |
| L6 | 48770 | 3 with 4 | US-PGPUB; USPAT | OR | ON | 2005/10/24 18:53 |
| L7 | 1085 | 5 and 6 | US-PGPUB; USPAT | OR | ON | 2005/10/24 18:53 |
| L8 | 1727138 | (active or device or circuit or component).clm. | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:07 |
| L9 | 17991 | 3 with 4 with 8 | US-PGPUB; USPAT | OR | ON | 2005/10/24 18:54 |
| L10 | 461 | 5 and 9 | US-PGPUB; USPAT | OR | ON | 2005/10/24 18:54 |
| L11 | 636 | bevel\$ with 4 | US-PGPUB; USPAT | OR | ON | 2005/10/24 18:55 |
| L12 | 1 | 10 and 11 | US-PGPUB; USPAT | OR | ON | 2005/10/24 18:55 |
| L13 | 1 | 10 and bevel\$.clm. | US-PGPUB; USPAT | OR | ON | 2005/10/24 18:55 |
| L14 | 27 | 10 and soi | US-PGPUB; USPAT | OR | ON | 2005/10/24 18:56 |
| L15 | 434 | 10 not 14 | US-PGPUB; USPAT | OR | ON | 2005/10/24 18:56 |
| L16 | 27 | 10 not 15 | US-PGPUB; USPAT | OR | ON | 2005/10/24 18:56 |
| L17 | 27 | 16 not 12 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:00 |
| L18 | 12038 | intel.as. | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:00 |
| L19 | 16 | 1 and 2 and 3 and 4 and 18 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:00 |
| L20 | 0 | 19 and bevel\$.clm. | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:01 |
| L21 | 11 | 19 and 8 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:02 |
| L22 | 473 | (morrow-p\$ or list-r\$ or chan-m\$).in. | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:03 |

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|-----|---------|---|--------------------|----|----|------------------|
| L23 | 2 | 1 and 2 and 3 and 4 and 22 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:04 |
| L24 | 10 | 1 and 2 and 3 and bevel\$ and 8 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:05 |
| L25 | 0 | 24 and 18 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:05 |
| L26 | 1 | 24 and 22 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:05 |
| L27 | 501246 | resist or photoresist or mask or photomask | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:22 |
| L28 | 2536837 | etch\$ or patern\$ or remov\$ | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:23 |
| L29 | 943762 | bond\$ or laminat\$ | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:23 |
| L30 | 3899085 | active or device or circuit or component | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:24 |
| L31 | 109495 | bevel\$ | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:24 |
| L32 | 9634 | 27 same 28 same 29 same 30 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:08 |
| L33 | 1209942 | wafer or semiconduct\$ or chip or substrate | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:23 |
| L34 | 6625 | 32 same 33 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:09 |
| L35 | 71065 | 27 with 28 with 33 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:10 |
| L36 | 68242 | 29 with 30 with 33 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:11 |
| L37 | 1339 | 34 same 35 same 36 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:11 |
| L38 | 1 | 31 same 37 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:12 |
| L39 | 1339 | 35 same 36 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:13 |
| L40 | 12 | 39 and bevel\$ | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:13 |
| L41 | 1 | 40 and (soi or "si\$ on insulat\$") | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:17 |
| L42 | 11 | 40 not 41 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:17 |
| L43 | 156 | 35 and 36 and bevel\$ | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:17 |
| L44 | 26 | 43 and (soi or "si\$ on insulat\$") | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:18 |
| L45 | 9869 | 35 and 36 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:18 |

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|-----|---------|--|--------------------|----|----|------------------|
| L46 | 9843 | 45 not 44 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:18 |
| L47 | 26 | 45 not 46 | US-PGPUB; USPAT | OR | ON | 2005/10/24 19:19 |
| L48 | 350861 | resist or photoresist or mask or photomask | JPO; DERWENT | OR | ON | 2005/10/24 19:22 |
| L49 | 1711071 | etch\$ or patern\$ or remov\$ | JPO; DERWENT | OR | ON | 2005/10/24 19:23 |
| L50 | 2064081 | wafer or semiconduct\$ or chip or substrate | JPO; DERWENT | OR | ON | 2005/10/24 19:23 |
| L51 | 994786 | bond\$ or laminat\$ | JPO; DERWENT | OR | ON | 2005/10/24 19:23 |
| L52 | 33963 | bevel\$ | JPO; DERWENT | OR | ON | 2005/10/24 19:24 |
| L53 | 8046801 | active or device or circuit or component | JPO; DERWENT | OR | ON | 2005/10/24 19:24 |
| L54 | 9 | 48 and 49 and 50 and 51 and 52 | JPO; DERWENT | OR | ON | 2005/10/24 19:25 |
| L55 | 5 | 53 and 54 | JPO; DERWENT | OR | ON | 2005/10/24 19:25 |
| L56 | 4 | 54 not 55 | JPO; DERWENT | OR | ON | 2005/10/24 19:26 |